

High Temperature Stability and High Reliability Conditions



DO-218AB

### FEATURES

- Chip produced by chemical method
- Junction passivated by high temperature resistant insulating adhesive
- $T_J = 175\text{ }^\circ\text{C}$  capability suitable for high reliability and automotive requirement
- Available in Bi-directional polarity only
- Low leakage current
- Low forward voltage drop
- High surge capability
- Meets ISO16750-2 surge specification (varied by test condition)
- LF maximum peak of  $245\text{ }^\circ\text{C}$
- AEC-Q101 qualified

PRIMARY CHARACTERISTICS	
$V_{BR}$	11.1 V to 52.8 V
$V_{WM}$	10 V to 43 V
$P_{PPM}$ (10 x 1000 $\mu\text{s}$ )	4600 W
$P_{PPM}$ (10 x 10 000 $\mu\text{s}$ )	3600 W
$P_D$	6 W
$T_J$ max.	$175\text{ }^\circ\text{C}$
Polarity	Unfi-dfirectional/Bi-directional
Package	DO-218AB

### TYPICAL APPLICATIONS

Use in sensitive electronics protection against voltage transients induced by inductive load switching and lighting, especially for automotive load dump protection application.

### MECHANICAL DATA

**Case:** DO-218AB

Molding compound meets UL 94 V-0 flammability rating  
Base P/NHE3\_X - RoHS-compliant and AEC-Q101 qualified  
("X" denotes revision code e.g. A, B, ...)

**Terminals:** matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

**Polarity:** heatsink is anode

MAXIMUM RATINGS ( $T_C = 25\text{ }^\circ\text{C}$ unless otherwise noted)				
PARAMETER		SYMBOL	VALUE	UNIT
Peak pulse power dissipation	with 10/1000 $\mu\text{s}$ waveform	$P_{PPM}$	4600	W
	with 10/10 000 $\mu\text{s}$ waveform		3600	
Power dissipation on infinite heatsink at $T_C = 25\text{ }^\circ\text{C}$ (fig. 1)		$P_D$	6.0	W
Peak pulse current with 10/1000 $\mu\text{s}$ waveform		$I_{PPM}^{(1)}$	See next table	A
Operating junction and storage temperature range		$T_J, T_{STG}$	-55 to +175	$^\circ\text{C}$

### Note

(1) Non-repetitive current pulse derated above  $T_A = 25\text{ }^\circ\text{C}$

<b>ELECTRICAL CHARACTERISTICS</b> ( $T_C = 25\text{ }^\circ\text{C}$ unless otherwise noted)										
DEVICE TYPE	BREAKDOWN VOLTAGE $V_{BR}$ (V)			TEST CURRENT $I_T$ (mA)	STAND-OFF VOLTAGE $V_{WM}$ (V)	MAXIMUM REVERSE LEAKAGE AT $V_{WM}$ $I_D$ ( $\mu\text{A}$ )	MAXIMUM REVERSE LEAKAGE AT $V_{WM}$ $T_J = 175\text{ }^\circ\text{C}$ $I_D$ ( $\mu\text{A}$ )	MAX. PEAK PULSE CURRENT AT 10/1000 $\mu\text{s}$ WAVEFORM (A)	MAXIMUM CLAMPING VOLTAGE AT $I_{PPM}$ $V_C$ (V)	TYPICAL TEMP. COEFFICIENT OF $V_{BR}$ $\alpha_T$ ( $\%/^\circ\text{C}$ )
	MIN.	NOM.	MAX.							
SM6S10(C)A-Q1	11.1	11.7	12.3	5.0	10.0	10	150	271	17.0	0.069
SM6S11(C)A-Q1	12.2	12.9	13.5	5.0	11.0	10	150	253	18.2	0.072
SM6S12(C)A-Q1	13.3	14.0	14.7	5.0	12.0	10	150	231	19.9	0.074
SM6S13(C)A-Q1	14.4	15.2	15.9	5.0	13.0	10	150	214	21.5	0.076
SM6S14(C)A-Q1	15.6	16.4	17.2	5.0	14.0	10	150	198	23.2	0.078
SM6S15(C)A-Q1	16.7	17.6	18.5	5.0	15.0	10	150	189	24.4	0.080
SM6S16(C)A-Q1	17.8	18.8	19.7	5.0	16.0	10	150	177	26.0	0.081
SM6S17(C)A-Q1	18.9	19.9	20.9	5.0	17.0	10	150	167	27.6	0.082
SM6S18(C)A-Q1	20.0	21.1	22.1	5.0	18.0	10	150	158	29.2	0.083
SM6S20(C)A-Q1	22.2	23.4	24.5	5.0	20.0	10	150	142	32.4	0.085
SM6S22(C)A-Q1	24.4	25.7	26.9	5.0	22.0	10	150	130	35.5	0.086
SM6S24(C)A-Q1	26.7	28.1	29.5	5.0	24.0	10	150	118	38.9	0.087
SM6S26(C)A-Q1	28.9	30.4	31.9	5.0	26.0	10	150	109	42.1	0.088
SM6S28(C)A-Q1	31.1	32.8	34.4	5.0	28.0	10	150	101	45.4	0.089
SM6S30(C)A-Q1	33.3	35.1	36.8	5.0	30.0	10	150	95	48.4	0.090
SM6S33(C)A-Q1	36.7	38.7	40.6	5.0	33.0	10	150	86	53.3	0.091
SM6S36(C)A-Q1	40.0	42.1	44.2	5.0	36.0	10	150	79	58.1	0.091
SM6S40(C)A-Q1	44.4	46.8	49.1	5.0	40.0	10	150	71	64.5	0.092
SM6S43(C)A-Q1	47.8	50.3	52.8	5.0	43.0	10	150	66	69.4	0.093

### Notes

(1) To calculate  $V_{BR}$  vs. junction temperature, use the following formula:  $V_{BR}$  at  $T_J = V_{BR}$  at  $25\text{ }^\circ\text{C} \times (1 + \alpha_T \times (T_J - 25))$

<b>ORDERING INFORMATION</b> (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PACKAGE	BASE QUANTITY	DELIVERY MODE
SM6SXX(C)A-Q1	2.85	DO-218AB	NA	According to customer's requirement

**RATINGS AND CHARACTERISTICS CURVES** ( $T_A = 25\text{ }^\circ\text{C}$  unless otherwise noted)

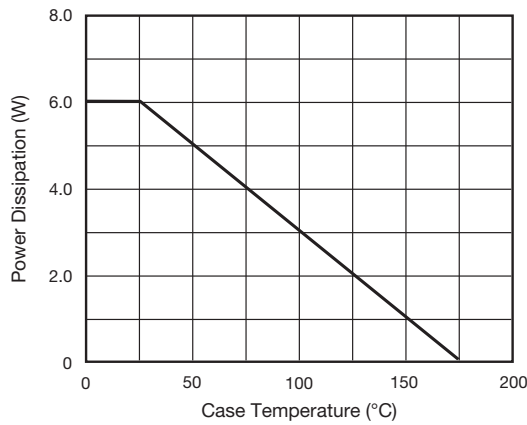


Fig. 1 - Power Derating Curve

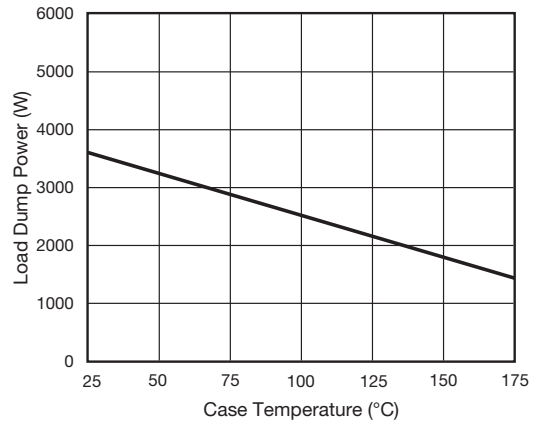


Fig. 2 - Load Dump Power Characteristics (10 ms Exponential Waveform)

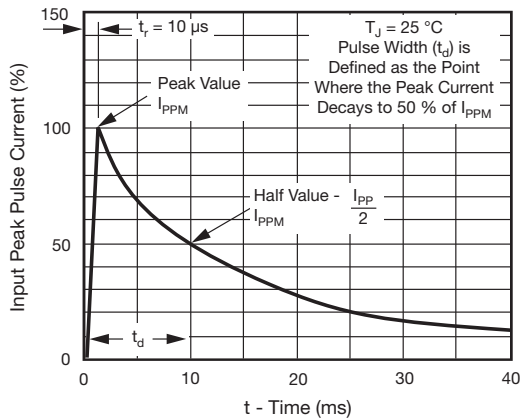


Fig. 3 - Pulse Waveform

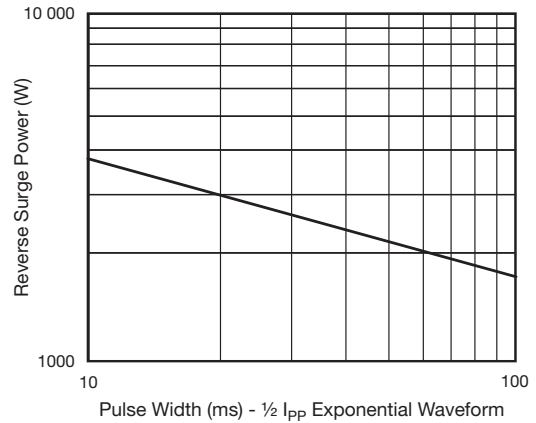


Fig. 4 - Reverse Power Capability

**PACKAGE OUTLINE DIMENSIONS** (millimeters)

